



FEATURES

- ◇ 6000 Watts peak pulse power dissipation($t_P=8/20\mu s$)
- ◇ Low leakage current
- ◇ Low clamping voltage
- ◇ Solid-state silicon-avalanche technology
- ◇ RoHS compliant

MAIN APPLICATIONS

- ◇ Power lines
- ◇ Personal digital assistants (PDA's)
- ◇ Microprocessors based equipment
- ◇ Notebooks, desktops, and servers
- ◇ Cell phone handsets and accessories
- ◇ Portable electronics
- ◇ Peripherals

PROTECTION SOLUTION TO MEET

- ◇ IEC61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- ◇ IEC61000-4-4 (EFT) 40A (5/50ns)
- ◇ IEC61000-4-5 (Lightning) 120A (8/20 μs)

MECHANICAL CHARACTERISTICS

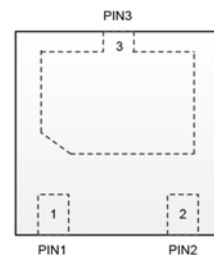
- ◇ DFN2x2-3L package
- ◇ Molding compound flammability rating: UL 94V-0
- ◇ Quantity per reel: 3,000pcs
- ◇ Lead finish: lead free
- ◇ Marking code: T24



DFN2x2-3L



Circuit Diagram



Pin Configuration

ABSOLUTE MAXIMUM RATINGS (T_A=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20μs waveform	P _{PP}	6000	W
ESD per IEC 61000-4-2 (Air)	V _{ESD}	+/- 30	kV
ESD per IEC 61000-4-2 (Contact)		+/- 30	
Lead soldering temperature	T _L	260 (10 sec.)	°C
Operating junction temperature range	T _J	-55 to +125	°C
Storage temperature range	T _{STG}	-55 to +150	°C

ELECTRICAL CHARACTERISTICS (T_A=25°C)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V _{RWM}				24	V
Reverse breakdown voltage	V _{BR}	I _T =1mA	26	27	30	V
Reverse leakage current	I _R	V _{RWM} =24V			1	μA
Clamping voltage	V _C	I _{PP} =50A, t _p =8/20μs		45	50	V
		I _{PP} =120A, t _p =8/20μs		52	60	
Junction capacitance	C _J	V _{RWM} =0V, f=1MHz		750		pF

RATINGS AND V-I CHARACTERISTICS CURVES (T_A=25°C, unless otherwise noted)

FIG.1: V- I curve characteristics (Uni-directional)

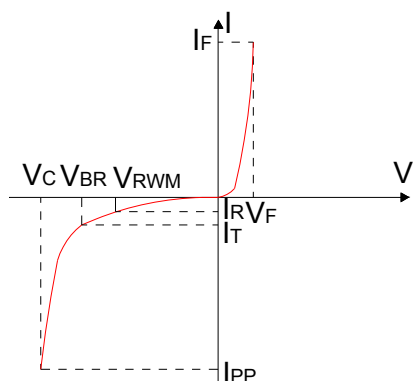


FIG.2: Pulse waveform (8/20μs)

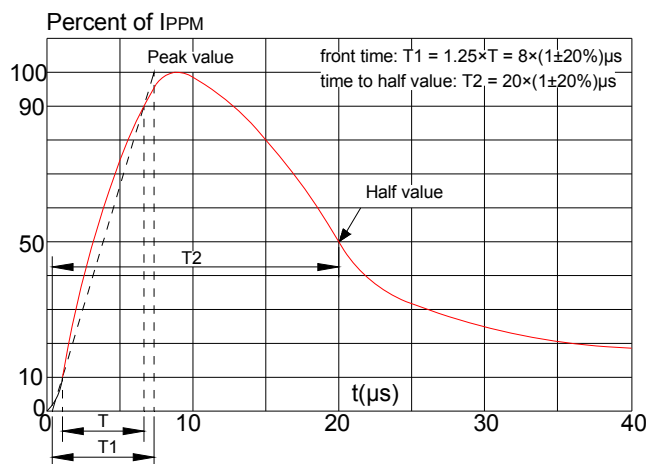


FIG.3: Pulse derating curve

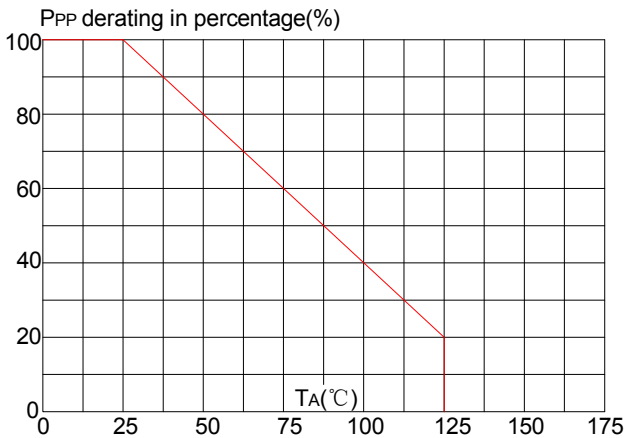


FIG.4: ESD clamping (30kV contact)

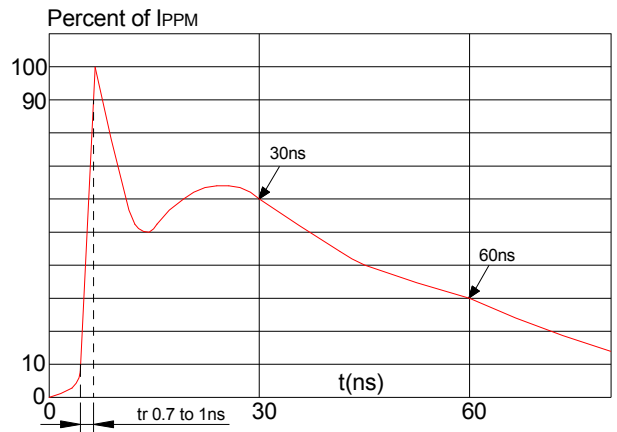


FIG.5: Clamping voltage vs.peak pulse current

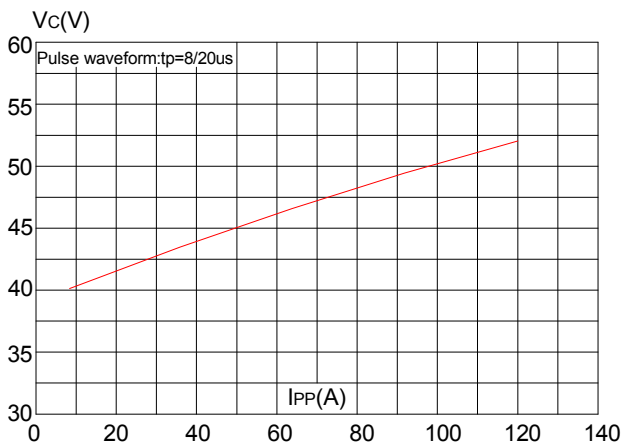
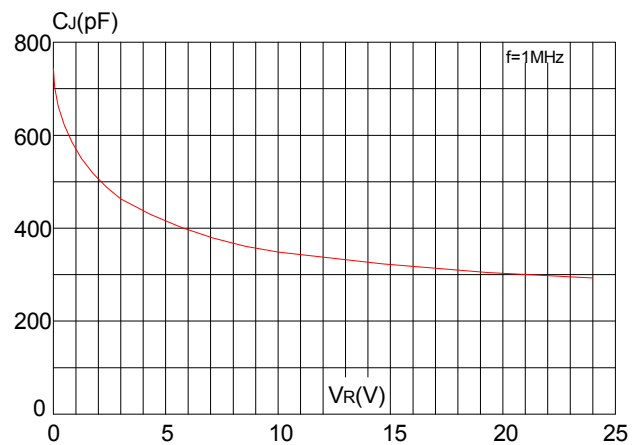
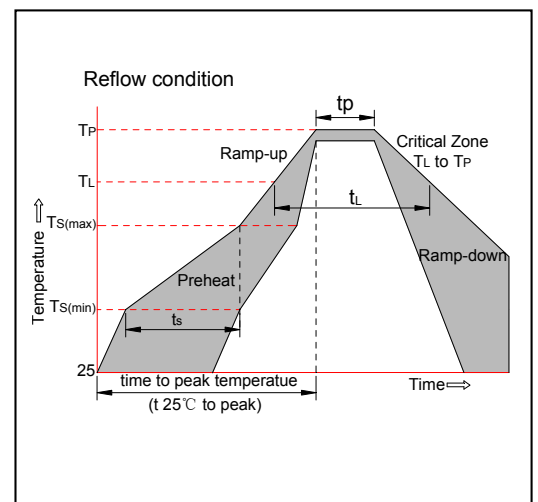


FIG.6: Capacitance vs.reverse voltage

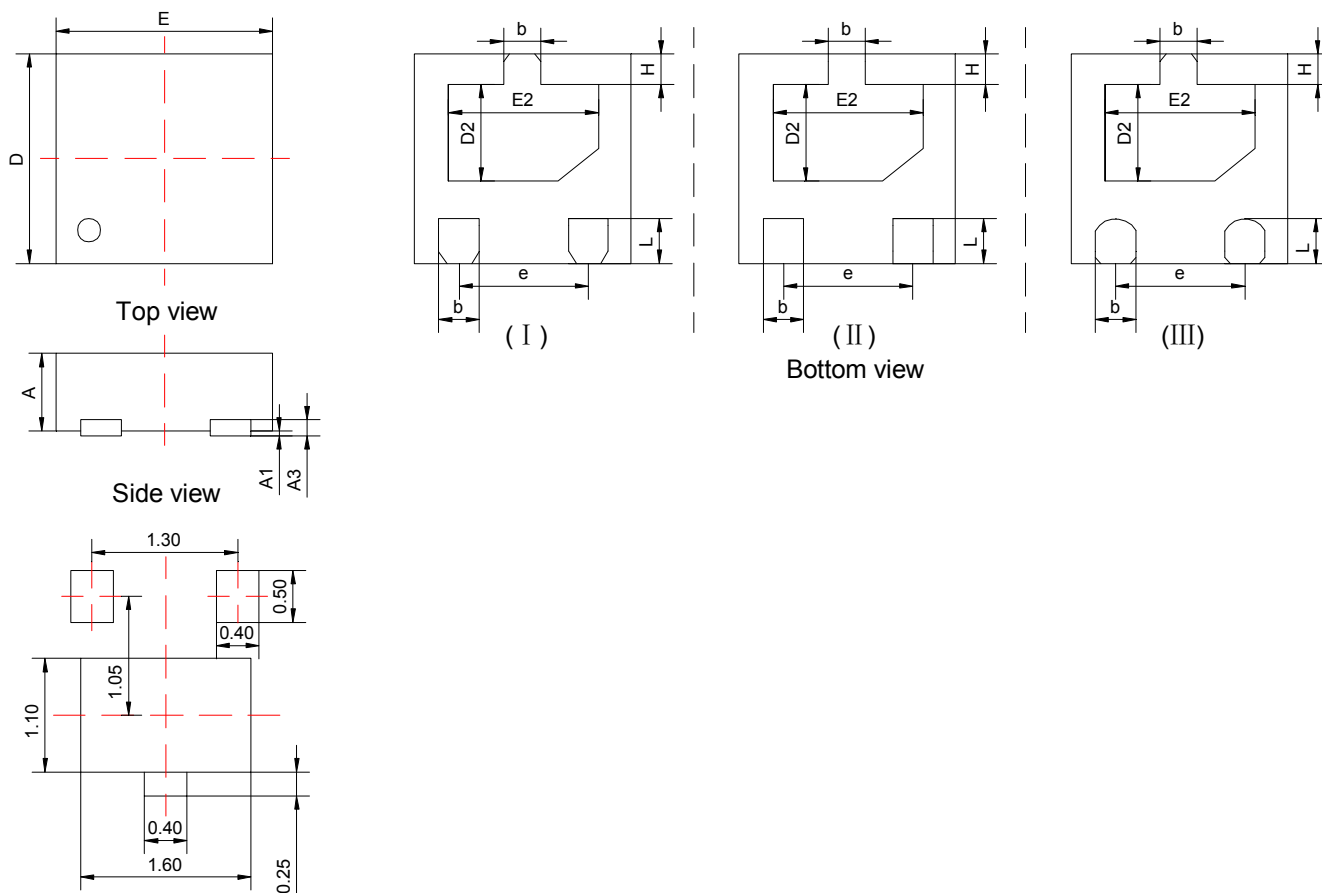


SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min (Ts(min))	+150°C
	-Temperature Max(Ts(max))	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (TL) to peak)		3°C/sec. Max
Ts(max) to TL - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(TL)(Liquidus)	+217°C
	-Temperature(tL)	60-150 secs.
Peak Temp (Tp)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (tp)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (Tp)		8 min. Max
Do not exceed		+260°C



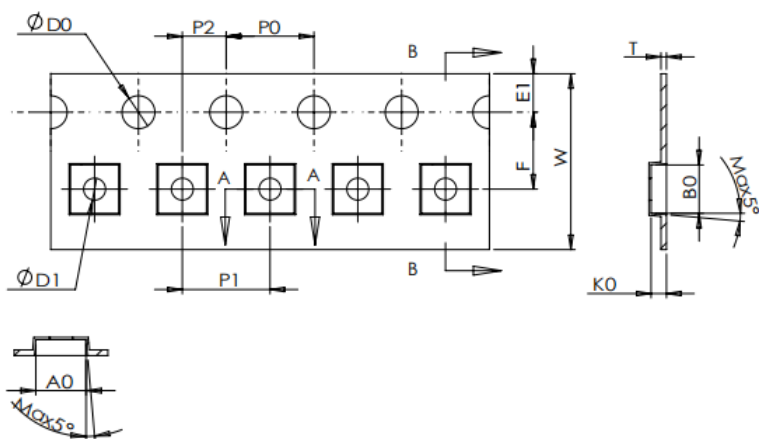
PACKAGE MECHANICAL DATA



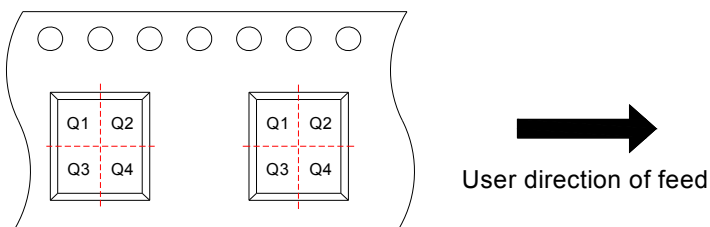
Recommended soldering footprint(mm)

Symbol	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.45	0.50	0.60	0.018	0.020	0.024
A1	0.00	0.02	0.05	0.000	0.001	0.002
A3	0.15REF			0.006REF		
b	0.25	0.30	0.35	0.010	0.012	0.014
D	1.90	2.00	2.10	0.075	0.079	0.083
E	1.90	2.00	2.10	0.075	0.079	0.083
D2	0.85	1.05	1.15	0.033	0.041	0.045
E2	1.40	1.50	1.60	0.055	0.059	0.063
e	1.30BSC			0.051BSC		
H	0.20	0.25	0.30	0.008	0.010	0.012
L	0.35	0.40	0.45	0.014	0.016	0.018

TAPE AND REEL INFORMATION-DFN2x2-3L



Symbol	Dimensions	
	Millimeters	Inches
	Typ.	Typ.
W	8.00	0.315
P1	4.00	0.157
E1	1.75	0.069
F	3.50	0.138
D0	1.55	0.061
D1	1.00	0.039
P0	4.00	0.157
P1	4.00	0.157
P2	2.00	0.079
A0	2.20	0.087
B0	2.20	0.087
K0	0.70	0.028
T	0.23	0.009

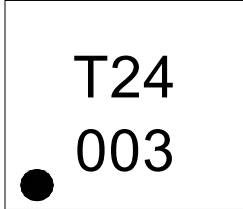


Pin 1 quadrant: Q3

ORDERING INFORMATION

PART No.	PACKAGE TYPE	QUANTITY(PCS) REEL	DESCRIPTION
JEU24N3	DFN2x2-3L	3,000	7 Inch

MARKING CODE

Part Number	Marking Code
JEU24N3	<div style="border: 1px solid black; padding: 10px; display: inline-block;">  </div>

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